introducing said adhesive paste into said at least one via hole in said at least one insulating layer, and,

subjecting the combination of said adhesive paste in said at least one via hole in said at least one insulating layer to a vehicle curing cycle including heat of the order of said low melting temperature of said metal and pressure.

Kindly rewrite the combination of claims 10 and 12, including the change of preamble specified in the objection on page 2 of the office action of 7/19/00 as claim 15 as follows.

15. A method of manufacturing an electronic apparatus comprising the serial combination of the steps of:

providing an adhesive paste,

said adhesive paste having random sizes of 5 -7 micrometer diameter range Cu particles each coated BiSn suspended in a vehicle of a mixture of cyclo-aliphatic epoxy, phenoxy polymer, mono-functional limonene oxide and a flux, in a proportion of epoxy 43%, phenoxy polymer 10%, mono-functional limonene oxide 43%, and flux 4%,

introducing said adhesive paste into said at least one via hole in said at least one insulating layer, and,

subjecting the combination of said adhesive paste in said at least one via hole in said at least one insulating layer to a vehicle curing cycle including heat of the order of said low melting temperature of said metal and pressure.

Kindly rewrite the combination of claims 10 and 13, including the change of preamble specified in the objection on page 2 of the office action of 7/19/00 as claim 16 as follows then cancel claims 10 and 13.

16. A method for manufacturing an electronic apparatus comprising the serial combination of the steps of:

providing an adhesive paste,

said adhesive paste having random sizes of 5 -7 micrometer diameter range Cu particles each coated BiSn suspended in a vehicle of a mixture of cyclo-aliphatic epoxy, phenoxy polymer, mono-functional limonene oxide and a flux,in a proportion of epoxy 4%, phenoxy polymer 4%, mono-functional limonene oxide 88%, and flux 4%,

introducing said adhesive paste into said at least one via hole in said at least one insulating layer, and,

subjecting the combination of said adhesive paste in said at least one via hole in said at least one insulating layer to a vehicle curing cycle including heat of the order of said low melting temperature of said metal and pressure.

In the Specification:

Page 2 line 13 Replace " formiing" with - forming-.

Page 3 lines 4 and 5 Erase " In Patent Applications, Ser.No. Filed (IBM Docket YO997-089) and Ser.No. Filed (IBM Docket YO998-196) " and in lieu thereof insert - In U.S. Patent 6,059,952 and Patent Application Ser. No. 09/078,043 Filed May 13,1998 - .